



HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTNFR520NH BK337 is an unreinforced, flame retardant high performance polyamide resin. It is also a PPA resin and it uses a non-halogenated flame retardant.

Product information Resin Identification Part Marking Code Part Marking Code	PA6T/66-FR(40) >PA6T/66-FR(40)< >PPA FR<		ISO 1043 ISO 11469 SAE J1344
Rheological properties	dry/cond.		
Moulding shrinkage, parallel Moulding shrinkage, normal	1.2/- 1.4/-	% %	ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile modulus	3700/3600	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	*/47	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min Tensile stress at break, 5mm/min	*/3.5 65/*	% MPa	ISO 527-1/-2 ISO 527-1/-2
Nominal strain at break	*/13	wra %	ISO 527-1/-2 ISO 527-1/-2
Tensile strain at break, 5mm/min	5.5/*	%	ISO 527-1/-2
Charpy impact strength, 23°C	45/60	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	2/2.5	kJ/m²	ISO 179/1eA
Poisson's ratio	0.36/0.36		
Thermal properties	dry/cond.		
Melting temperature, 10°C/min	310/*	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	95/60	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	104/*	°C	ISO 75-1/-2
Flammability	dry/cond.		
Burning Behav. at thickness h	V-0/*	class	IEC 60695-11-10
Thickness tested	0.4/*	mm	IEC 60695-11-10
Electrical properties	dry/cond.		
Comparative tracking index	600/-		IEC 60112
Physical/Other properties	dry/cond.		
Humidity absorption, 2mm	1.6/*	%	Sim. to ISO 62
Water absorption, 2mm	6.5/*	%	Sim. to ISO 62
Density	1220/-	kg/m³	ISO 1183
Injection			
Melt Temperature Optimum	325	°C	
Min. melt temperature	320		
Max. melt temperature	330		
Mold Temperature Optimum Min. mould temperature		°C °C	
min mode temperature	00	0	

Printed: 2025-05-30 Page: 1 of 11

Revised: 2025-01-15 Source: Celanese Materials Database





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Max. mould temperature 120 °C Ejection temperature 251 °C

Characteristics

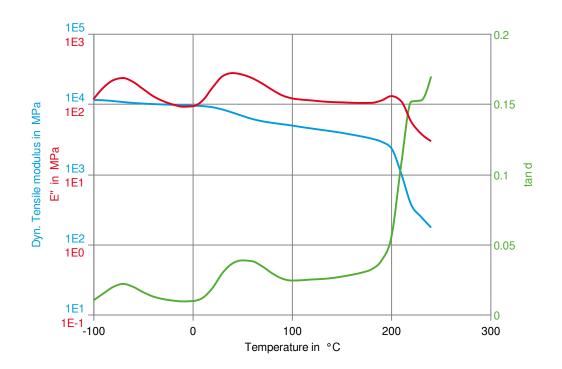
Processing Injection Moulding

Delivery form Pellets

Additives Flame retardant, Non-halogenated/Red phosphorous free flame retardant

Special characteristics Flame retardant, Heat stabilised or stable to heat

Dynamic Tensile modulus-temperature (dry)



Printed: 2025-05-30 Page: 2 of 11

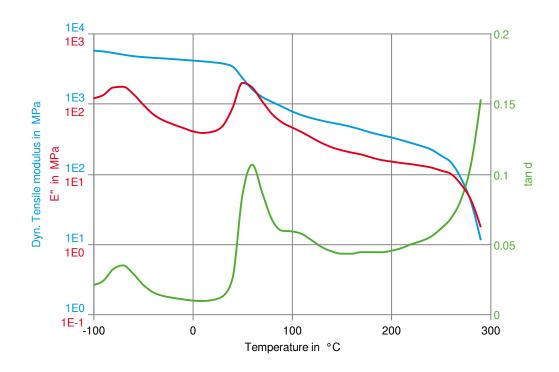
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Dynamic Tensile modulus-temperature (cond.)



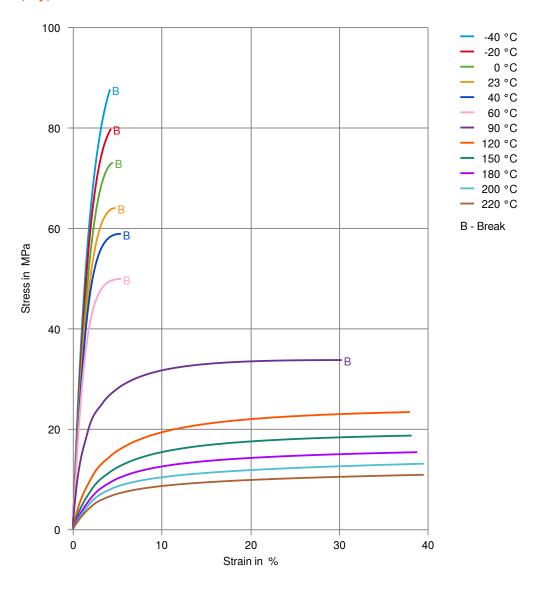
Printed: 2025-05-30 Page: 3 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

Stress-strain (dry)



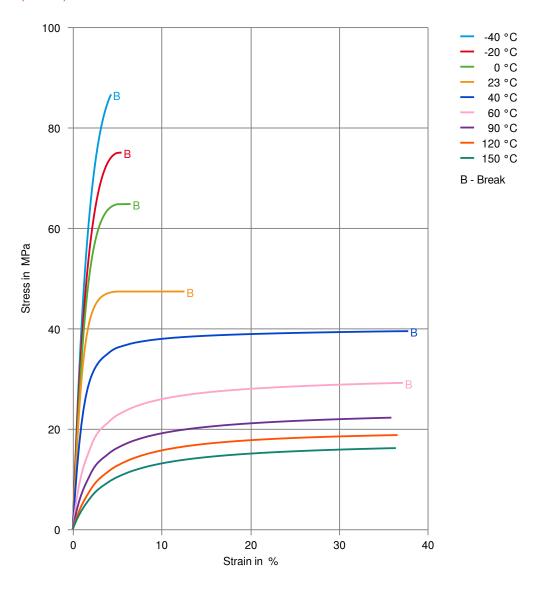
Printed: 2025-05-30 Page: 4 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

Stress-strain (cond.)



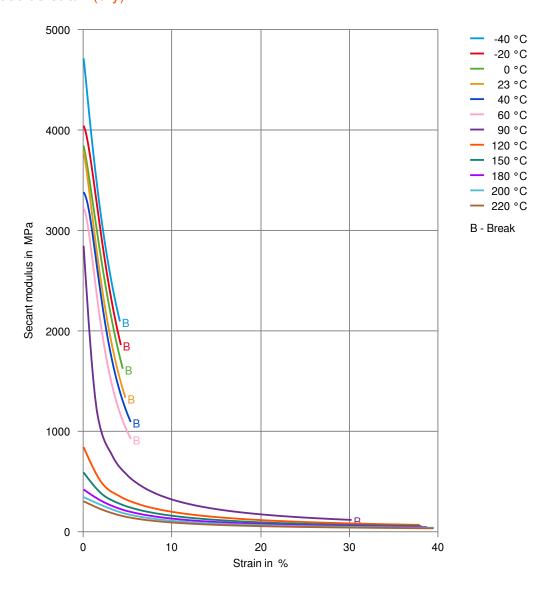
Printed: 2025-05-30 Page: 5 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

Secant modulus-strain (dry)



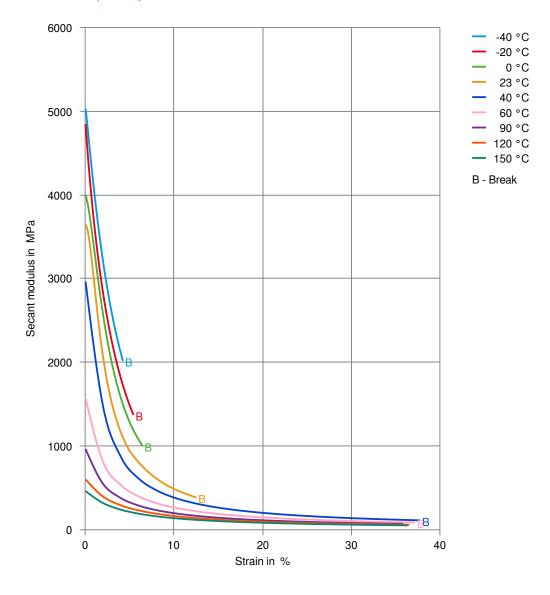
Printed: 2025-05-30 Page: 6 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

Secant modulus-strain (cond.)



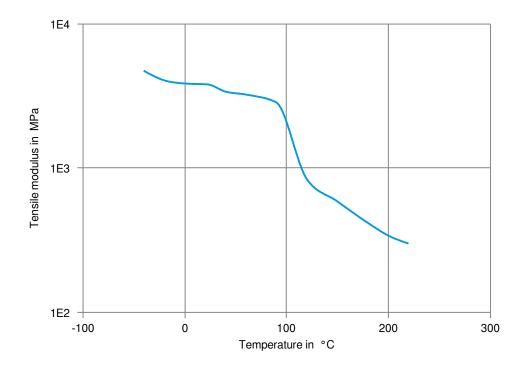
Printed: 2025-05-30 Page: 7 of 11





Zytel® HTNFR520NH BK337 HIGH PERFORMANCE POLYAMIDE RESIN

Tensile modulus-temperature (dry)



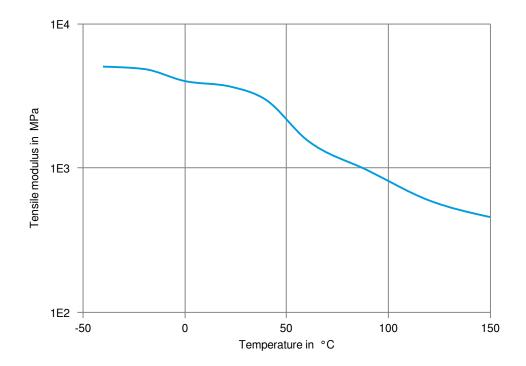
Printed: 2025-05-30 Page: 8 of 11





Zytel® HTNFR520NH BK337 HIGH PERFORMANCE POLYAMIDE RESIN

Tensile modulus-temperature (cond.)



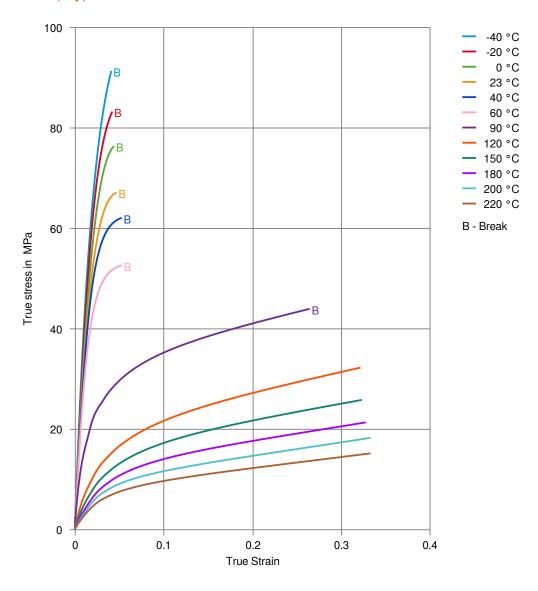
Printed: 2025-05-30 Page: 9 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

True stress-strain (dry)



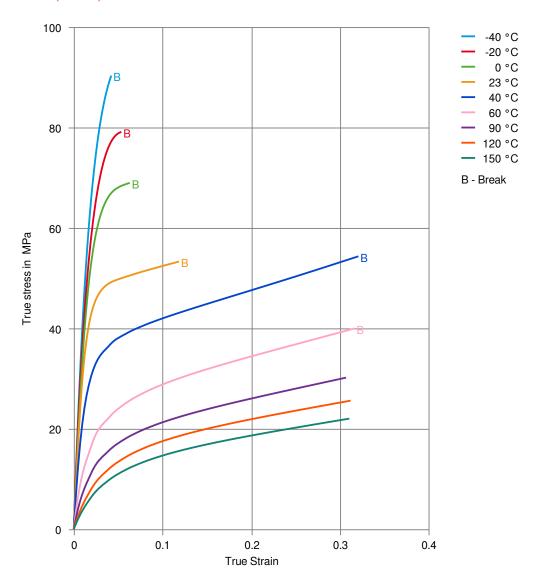
Printed: 2025-05-30 Page: 10 of 11





HIGH PERFORMANCE POLYAMIDE RESIN

True stress-strain (cond.)



Printed: 2025-05-30 Page: 11 of 11

Revised: 2025-01-15 Source: Celanese Materials Database

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